

Solid State Relay OCMOS FET PS7200E-1A

4-PIN SOP, 0.8 Ω LOW ON-STATE RESISTANCE 1-ch Optical Coupled MOS FET

-NEPOC Series-

DESCRIPTION

The PS7200E-1A is a low on-state resistance solid state relay containing a GaAs LED on the light emitting side (input side) and MOS FETs on the output side.

It is suitable for high-frequency signal control due to its low $C \times R$, low on-state resistance, and low off-state leakage current.

FEATURES

- Low ERT (ERT = 78 ps TYP.)
- Low $C \times R$ ($C \times R = 27 \text{ pF} \bullet \Omega$)
- Low on-state resistance (Ron = 0.8 Ω TYP.)
- Low off-state leakage current
- 1 channel type (1 a output)
- Designed for AC/DC switching line changer
- Small and thin package (4-pin SOP, Height = 2.1 mm)
- High isolation voltage (BV = 1 500 Vr.m.s.)
- · Low offset voltage
- Ordering number of taping product : PS7200E-1A-E3, E4: 900 pcs/reel

: PS7200E-1A-F3, F4: 3 500 pcs/reel

<R> • Pb-Free product

APPLICATIONS

Measurement equipment

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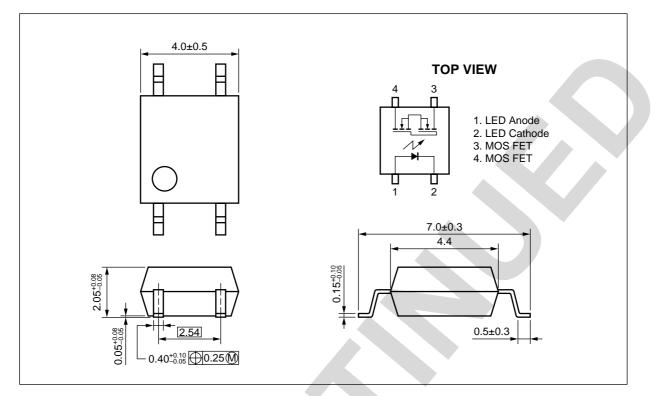
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The mark <R> shows major revised points.

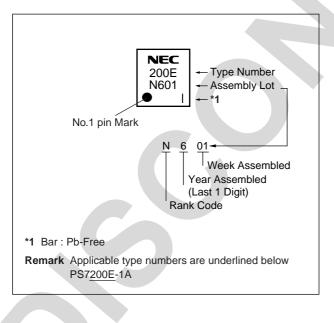
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The revised points can be easily searched by copying an "<R>" in the PDF file and specifying it in the "Find what:" field.

PACKAGE DIMENSIONS (Unit : mm)



<R> MARKING EXAMPLE (LASER MARKING)



<R> ORDERING INFORMATION

Part Number	Order Number	Solder Plating Specification	Packing Style
PS7200E-1A	PS7200E-1A-A	Pb-Free	Magazine case 100 pcs
PS7200E-1A-E3	PS7200E-1A-E3-A		Embossed Tape 900 pcs/reel
PS7200E-1A-E4	PS7200E-1A-E4-A		
PS7200E-1A-F3	PS7200E-1A-F3-A		Embossed Tape 3 500 pcs/reel
PS7200E-1A-F4	PS7200E-1A-F4-A		

ABSOLUTE MAXIMUM RATINGS (TA = 25°C, unless otherwise specified)

Parameter		Symbol	Ratings	Unit
Diode	Forward Current (DC)	lF	50	mA
	Reverse Voltage	VR	5.0	V
	Power Dissipation	PD	50	mW
	Peak Forward Current *1	I FP	1	Α
MOS FET	Break Down Voltage	VL	40	V
	Continuous Load Current	Ŀ	250	mA
	Power Dissipation	P□	100	mW
Isolation Voltage *2		BV	1 500	Vr.m.s.
Total Power Dissipation		Р⊤	150	mW
Operating Ambient Temperature		TA	-40 to +85	°C
Storage Temperature		Tstg	-40 to +100	°C

***1** PW = 100 μs, Duty Cycle = 1%

*2 AC voltage for 1 minute at $T_A = 25^{\circ}C$, RH = 60% between input and output Pins 1-2 shorted together, 3-4 shorted together.

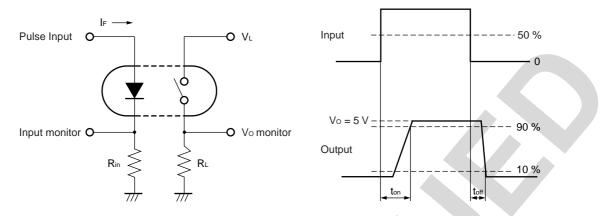
RECOMMENDED OPERATING CONDITIONS (TA = 25°C)

Parameter	Symbol	MIN.	TYP.	MAX.	Unit
LED Operating Current	lF	2	5	20	mA
LED Off Voltage	VF	0		0.5	V

	Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Diode	Forward Voltage	VF	IF = 5 mA		1.1	1.4	V
	Reverse Current	Ir	V _R = 5 V			5.0	μA
MOS FET	Off-state Leakage Current	Loff	V _D = 40 V		0.1	10	nA
	Output Capacitance	Cout	V _D = 0 V, f = 1 MHz		33.5		pF
Coupled	LED On-state Current	IFon	I∟ = 250 mA			2.0	mA
	On-state Resistance	Ron1	I⊧ = 5 mA, I∟ = 10 mA		0.8	1.6	Ω
		Ron2	I_{F} = 5 mA, I_{L} = 250 mA, $t \leq$ 10 ms		0.8	1.6	
	Turn-on Time ^{*1, 2}	ton	I⊧ = 5 mA, V₀ = 5 V, R∟ = 500 Ω,		0.48	1.0	ms
	Turn-off Time ^{*1, 2}	toff	PW ≥ 10 ms		0.15	0.5	
	Isolation Resistance	Ri-o	VI-0 = 1.0 kVDC	10 ⁹			Ω
	Isolation Capacitance	CI-0	V = 0 V, f = 1 MHz		0.5		pF
	Equivalent Rise Time ^{*3}	ERT	I _F = 10 mA, tr _(in) = 25 ps, V = 250 mV, 50 Ω termination		78		ps

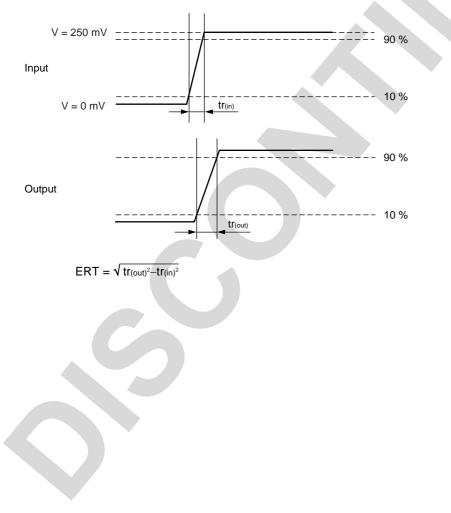
ELECTRICAL CHARACTERISTICS (TA = 25°C)

<R> *1 Test Circuit for Switching Time

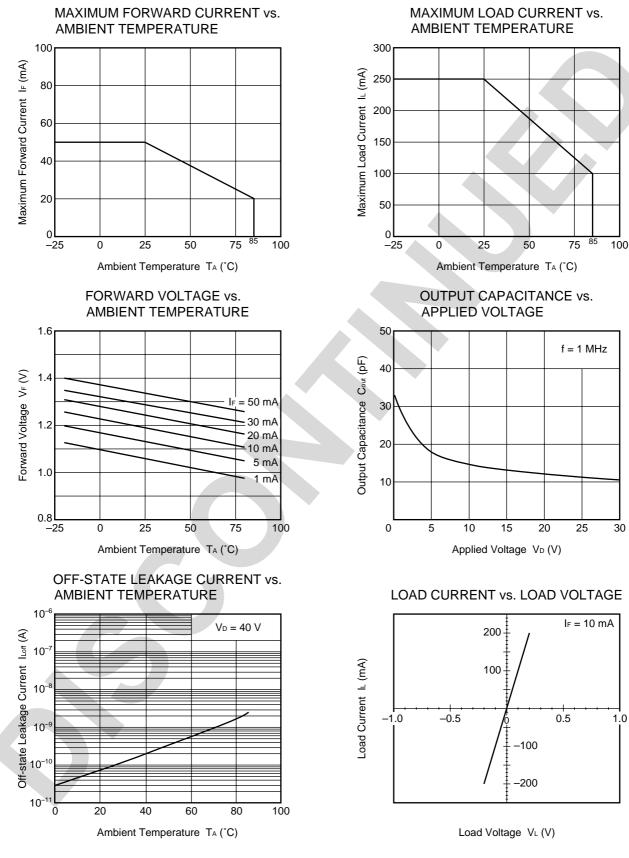


*2 The turn-on time and turn-off time are specified as input-pulse width ≥ 10 ms.
 Be aware that when the device operates with an input-pulse width less than 10 ms, the turn-on time and turn-off time will increase.

*3 ERT waveform and equation



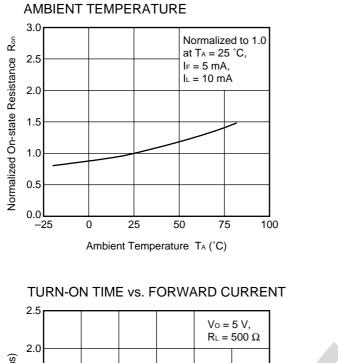
TYPICAL CHARACTERISTICS (TA = 25°C, unless otherwise specified)

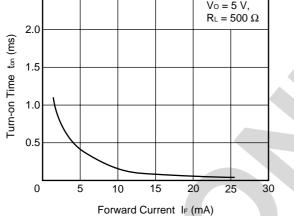




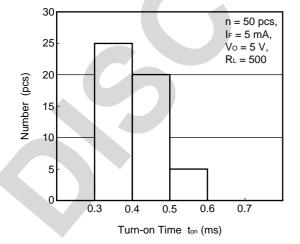
Data Sheet PN10293EJ02V0DS

NORMALIZED ON-STATE RESISTANCE vs.



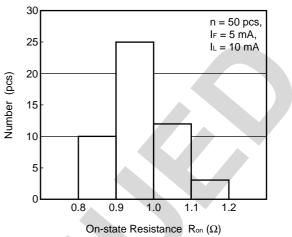


TURN-ON TIME DISTRIBUTION

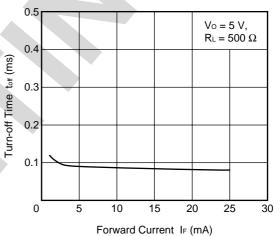


Remark The graphs indicate nominal characteristics.

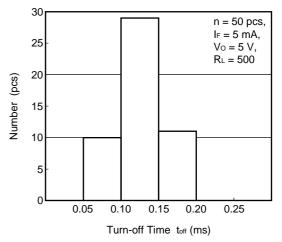
ON-STATE RESISTANCE DISTRIBUTION

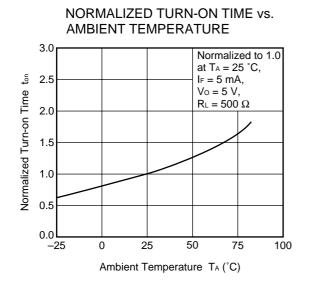


TURN-OFF TIME vs. FORWARD CURRENT

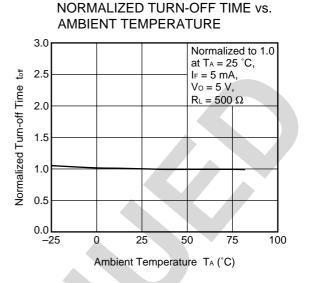


TURN-OFF TIME DISTRIBUTION

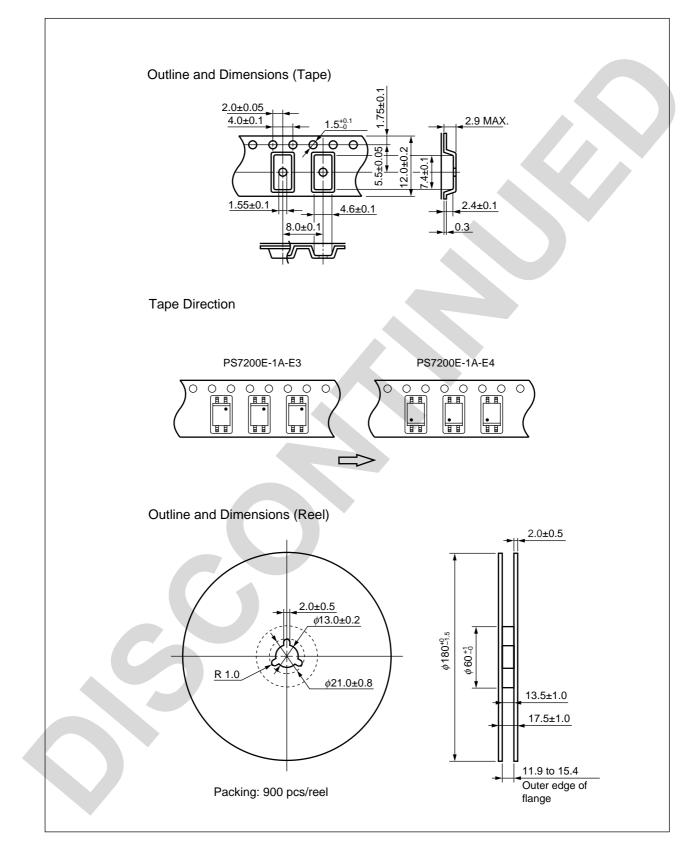


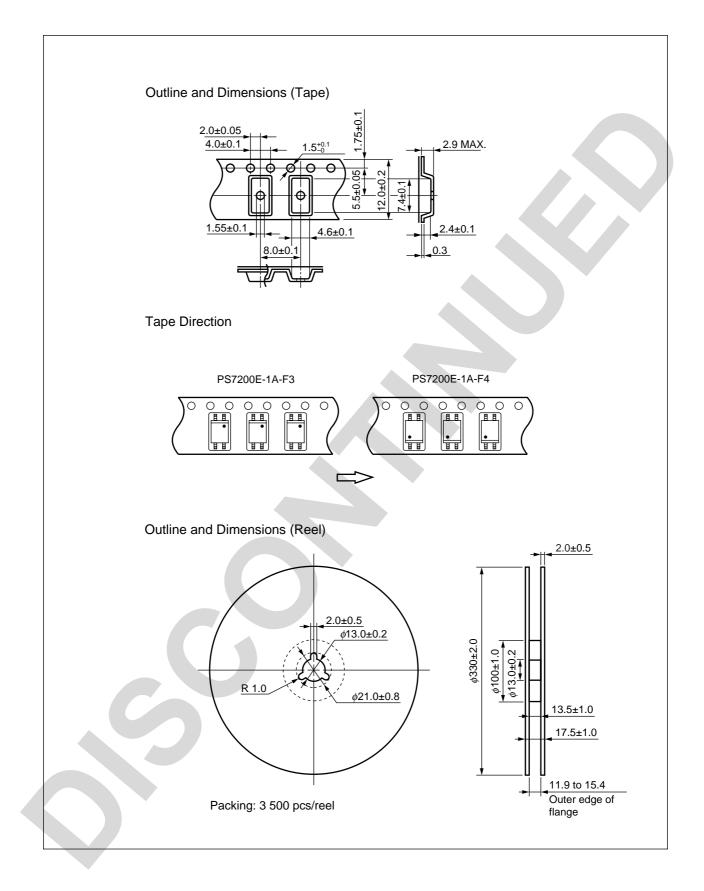






TAPING SPECIFICATIONS (Unit : mm)





RECOMMENDED SOLDERING CONDITIONS

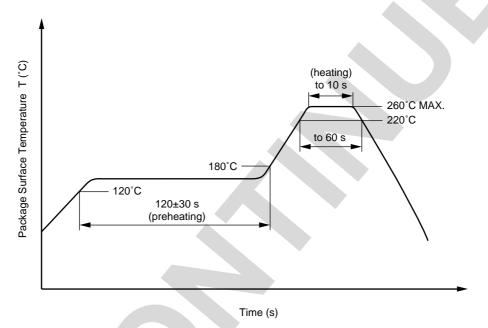
(1) Infrared reflow soldering

- Peak reflow temperature
- Time of peak reflow temperature
- Time of temperature higher than 220°C
- Time to preheat temperature from 120 to 180°C
- Number of reflows
- Flux

260°C or below (package surface temperature) 10 seconds or less 60 seconds or less 120±30 s Three

Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt% is recommended.)

Recommended Temperature Profile of Infrared Reflow



(2) Wave soldering

 Temperature

- Time
- Preheating conditions 120°C or below (package surface temperature)
- Number of times
- Flux

One Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt% is recommended.)

<R> (3) Soldering by soldering iron

350°C or below
3 seconds or less
Rosin flux containing small amount of chlorine (The flux with a
maximum chlorine content of 0.2 Wt% is recommended.)

260°C or below (molten solder temperature)

10 seconds or less

(a) Soldering of leads should be made at the point 1.5 to 2.0 mm from the root of the lead.

(b) Please be sure that the temperature of the package would not be heated over 100°C.

(4) Cautions

• Fluxes

Avoid removing the residual flux with freon-based and chlorine-based cleaning solvent.

<R> USAGE CAUTIONS

- **1.** Protect against static electricity when handling.
- 2. Avoid storage at a high temperature and high humidity.

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M8E 02.11-1

Caution GaAs Products	This product uses gallium arsenide (GaAs). GaAs vapor and powder are hazardous to human health if inhaled or ingested, so please observe the following points.
	• Follow related laws and ordinances when disposing of the product. If there are no applicable laws and/or ordinances, dispose of the product as recommended below.
	 Commission a disposal company able to (with a license to) collect, transport and dispose of materials that contain arsenic and other such industrial waste materials.
	2. Exclude the product from general industrial waste and household garbage, and ensure that the product is controlled (as industrial waste subject to special control) up until final disposal.
	• Do not burn, destroy, cut, crush, or chemically dissolve the product.
	Do not lick the product or in any way allow it to enter the mouth.

▶ For further information, please contact

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